

Final Product Change Notification

202211029F01 : i.MX RT1064 Assembly Site Expansion from ASEKH to TFME-S

Note: This notice is NXP Company Proprietary.

Issue Date: Dec 24, 2022 Effective date:Mar 24, 2023

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Management summary

Assembly site expansion for i.MX RT1064 with this notification, from the current Site ASE Kaohsiung, Taiwan (ASEKH) assembly facility to TFME Sutong, Jiangsu, China (TFME-S) assembly facility.

Change Category

F 71.4.4.4

	[]Wafer Fab Process	[]Assembly Process	[X]Product Marking	[]Test Process	[]Design
	[]Wafer Fab Materials	[X]Assembly Materials	[]Mechanical Specification	[]Test Equipment	[]Errata
	[]Wafer Fab Location	[X]Assembly Location	[]Packing/Shipping/Labeling	[]Test Location	[]Electrical spec./Test coverage
[]Firmware []Other					

PCN Overview Description

NXP Semiconductors announces the Assembly site expansion for i.MX RT1064 with this notification, from the current Site ASE Kaohsiung, Taiwan (ASEKH) assembly facility to TFME Sutong, Jiangsu, China (TFME-S) assembly facility.

Assembly site expansion has been qualified adhering to NXP specifications.

Please see the attached file(s) for additional details.

Reason

NXP will release TFME Sutong (TFME-S) as a second source assembly site to increase manufacturing capabilities and security of supply.

Identification of Affected Products

The first two characters of the third line in the part marking will indicate assembly site: ZK=ASEKH TS=TFME-S.

Product Availability

Sample Information

Samples are available fromDec 31, 2022 Below are the sample part numbers that will be made available.

-PIMXRT1064DVL6B -PIMXRT1064CVL5B -PIMXRT1064DVJ6B -PIMXRT1064CVJ5B **Production** Planned first shipmentMar 20, 2023 **Anticipated Impact on Form, Fit, Function, Reliability or Quality**

No Impact on form, fit, function, reliability or quality **Disposition of Old Products** TFME-S will be an additional assembly site. Parts may continue to be assembled at ASEKH as well. **Additional information**

Self qualification:<u>view online</u> Additional documents: <u>view online</u> **Timing and Logistics**

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Jan 23, 2023.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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NXP Quality Management Team.

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